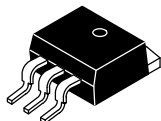


# MECHANICAL CASE OUTLINE

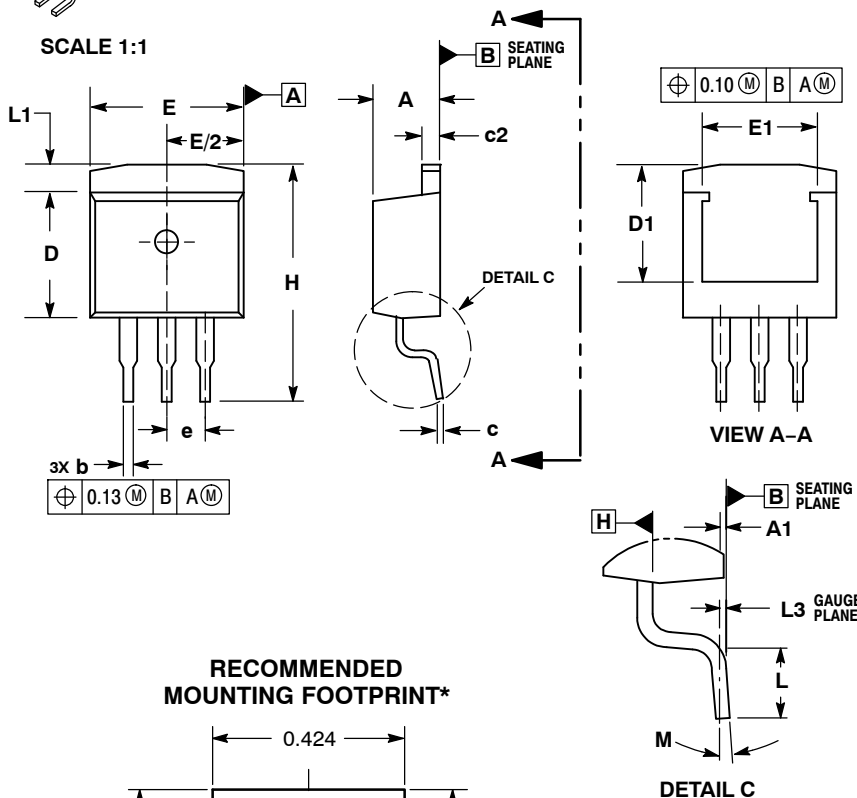
## PACKAGE DIMENSIONS

ON Semiconductor®



**D<sup>2</sup>PAK-3**  
CASE 418AB-01  
ISSUE A

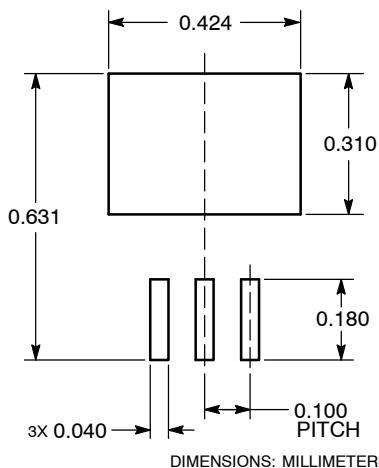
DATE 16 SEP 2009



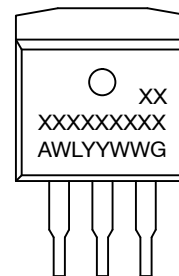
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: INCHES.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.005 MAXIMUM PER SIDE. THESE DIMENSIONS TO BE MEASURED AT DATUM H.
  4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E, L1, D1, AND E1. DIMENSIONS D1 AND E1 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THE THERMAL PAD.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.170	0.180	4.32	4.57
A1	0.000	0.010	0.00	0.25
b	0.026	0.036	0.66	0.91
c	0.017	0.026	0.43	0.66
c2	0.045	0.055	1.14	1.40
D	0.325	0.368	8.25	9.53
D1	0.270	---	6.86	---
E	0.380	0.420	9.65	10.67
E1	0.245	---	6.22	---
e	0.100 BSC		2.54 BSC	
H	0.580	0.620	14.73	15.75
L	0.090	0.110	2.29	2.79
L1	---	0.066	---	1.68
L3	0.010 BSC		0.25 BSC	
M	0°	8°	0°	8°

### RECOMMENDED MOUNTING FOOTPRINT\*



### GENERIC MARKING DIAGRAM\*



- XXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

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<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>D<sup>2</sup>PAK-3</b>	<b>PAGE 1 OF 2</b>



<b>ISSUE</b>	<b>REVISION</b>	<b>DATE</b>
O	RELEASED FOR PRODUCTION. REQ. BY J. KEISER	18 DEC 2003
A	CHANGES RELATED TO CARSEM TO SEREMBAN TRANSFER. REDREW TO JEDEC STANDARDS. ADDED SOLDER FOOTPRINT. REQ. BY B. FONTES.	16 SEP 2009

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